

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-7. Canceled

8. (Currently Amended) A component of semiconductor processing equipment, the component comprising a substrate having a surface and a liquid crystalline polymer coating on the surface and forming an outer surface thereof of the component, wherein the component is a ~~chamber liner made entirely of the liquid crystalline polymer and/or~~ a component other than a chamber liner.

9. Cancelled

10. (Currently Amended) The component according to Claim 9 8, wherein the substrate comprises aluminum or an aluminum alloy.

11. (Currently Amended) The component according to Claim 9 8, wherein the substrate comprises alumina.

12. (Previously Presented) The component according to Claim 10, wherein the substrate includes an anodized surface.

13. (Previously Presented) A component of semiconductor processing equipment, the component comprising a substrate including a surface and a plasma-sprayed liquid crystalline polymer coating on the surface.

14. (Currently Amended) The component according to Claim 8, wherein the component is a plasma chamber wall, a gas distribution plate, a gas ring, a pedestal, an electrostatic chuck ~~and/or~~ or a focus ring.

15. (Currently Amended) The component according to Claim 8, wherein the liquid crystalline polymer comprises a preformed sheet covering a the surface of a the substrate.

16. (Previously Presented) The component according to Claim 13, wherein the component comprises a roughened surface that has been subjected to a surface roughening treatment and is in contact with the plasma sprayed coating applied on the roughened surface.

17. (Original) The component according to Claim 8, wherein the liquid crystalline polymer contains a filler.

18. (Original) A plasma chamber comprising at least one component according to Claim 8.

19-23. Cancelled

24. (Currently Amended) The component according to Claim 13, wherein the component is a plasma chamber wall, a chamber liner, a gas distribution plate, a gas ring, a pedestal, an electrostatic chuck ~~and/or~~ or a focus ring.

25. (Currently Amended) ~~The component according to Claim 9, wherein the surface of the substrate is a bead or grit-blasted roughened surface which is mechanically keyed or interlocked with the coating.~~

A component of semiconductor processing equipment, the component comprising a liquid crystalline polymer on an outer surface thereof, wherein the liquid crystalline polymer comprises a coating on a bead or grit-blasted roughened surface of a substrate which is mechanically keyed or interlocked with the coating.

26. (Currently Amended) The component according to Claim 9 8, further comprising at least one intermediate layer between the surface of the substrate and the coating.

27. (Currently Amended) The component according to Claim 9 8, wherein the substrate is of stainless steel, a refractory metal or a polymeric material.

28. (Currently Amended) The component according to Claim 9 8, wherein the substrate is of a ceramic material selected from the group consisting of silicon carbide, silicon nitride, boron carbide and boron nitride.

29. (Currently Amended) ~~The component according to Claim 13, wherein the surface of the component is a bead or grit-blasted roughened surface which is mechanically keyed or interlocked with the plasma-sprayed coating applied on the roughened surface.~~

A component of semiconductor processing equipment, the component comprising a substrate including a bead or grit-blasted roughened surface and a plasma-sprayed liquid crystalline polymer coating on the roughened surface, wherein the roughened surface is mechanically keyed or interlocked with the plasma sprayed coating.

30. (Previously Presented) The component according to Claim 13, further comprising at least one intermediate layer between the surface of the component and the plasma sprayed coating.

31. (Previously Presented) The component according to Claim 13, wherein the substrate is of stainless steel, a refractory metal or a polymeric material.

32. (Previously Presented) The component according to Claim 13, wherein the substrate is of a ceramic material selected from the group consisting of silicon carbide, silicon nitride, boron carbide and boron nitride.